

**CLEANING SUBSTRATE FOR CLEANING  
AND REGENERATING A MOLD**

**ABSTRACT**

A cleaning substrate for cleaning and regenerating a mold is disclosed. The  
5 mold is contaminated after repeatedly packaging the semiconductor device by making  
use of thermosetting resin. At least a protrusion of the substrate can substantially  
match with and be contained within the edges of the mold cavity of the mold when the  
cleaning substrate is placed in the mold.

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